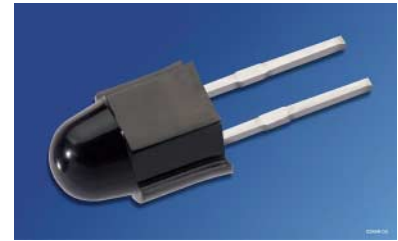


IR-Lumineszenzdiode (940nm) mit hoher Ausgangsleistung in SMR® Gehäuse
High Power Infrared Emitter (940nm) in SMR® Package
Lead (Pb) Free Product - RoHS Compliant

SFH 4542
SFH 4543



SFH 4542



SFH 4543

Wesentliche Merkmale

- Infrarot LED mit hoher Ausgangsleistung
- SMR® (Surface Mount Radial) Gehäuse
- Gehäusegleich mit Fotodiode SFH 2500
- Kurze Schaltzeiten

Anwendungen

- Sensorik
- Diskrete Lichtschranken
- Diskrete Optokoppler

Sicherheitshinweise

Je nach Betriebsart emittieren diese Bauteile hochkonzentrierte, nicht sichtbare Infrarot-Strahlung, die gefährlich für das menschliche Auge sein kann. Produkte, die diese Bauteile enthalten, müssen gemäß den Sicherheitsrichtlinien der IEC-Normen 60825-1 und 62471 behandelt werden.

Features

- High Power Infrared LED
- SMR® (Surface Mount Radial) package
- Same package as photodiode SFH 2500
- Short switching times

Applications

- Sensor technology
- Discrete interrupters
- Discrete optocouplers

Safety Advices

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

Typ Type	Bestellnummer Ordering Code	Strahlstärkegruppierung ¹⁾ ($I_F = 100 \text{ mA}$, $t_p = 20 \text{ ms}$) Radiant Intensity Grouping ¹⁾ I_e (mW/sr)
SFH 4542	Q65110A8093	≥ 63 (typ. 180)
SFH 4543	Q65110A8094	≥ 63 (typ. 180)

¹⁾ gemessen bei einem Raumwinkel $\Omega = 0.01 \text{ sr}$ / measured at a solid angle of $\Omega = 0.01 \text{ sr}$

Grenzwerte ($T_A = 25\text{ °C}$)**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	T_{op}, T_{stg}	- 40 ... + 85	°C
Sperrspannung Reverse voltage	V_R	5	V
Vorwärtsgleichstrom Forward current	I_F	100	mA
Stoßstrom, $t_p = 60\ \mu\text{s}$, $D = 0$ Surge current	I_{FSM}	1.5	A
Verlustleistung Power dissipation	P_{tot}	180	mW
Wärmewiderstand Sperrschicht - Umgebung bei Montage auf FR4 Platine, Padgröße je $20\ \text{mm}^2$ Thermal resistance junction - ambient mounted on PC-board (FR4), padsize $20\ \text{mm}^2$ each	R_{thJA}	300	K/W

Kennwerte ($T_A = 25\text{ °C}$)**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der Strahlung Wavelength at peak emission $I_F = 100\ \text{mA}$	λ_{peak}	950	nm
Centroid-Wellenlänge der Strahlung Centroid wavelength $I_F = 100\ \text{mA}$	$\lambda_{centroid}$	940	nm
Spektrale Bandbreite bei 50% von I_{max} Spectral bandwidth at 50% of I_{max} $I_F = 100\ \text{mA}$	$\Delta\lambda$	42	nm
Abstrahlwinkel Half angle	φ	± 10	Grad deg.
Aktive Chipfläche Active chip area	A	0.09	mm^2
Abmessungen der aktiven Chipfläche Dimension of the active chip area	$L \times B$ $L \times W$	0.3×0.3	mm^2

Kennwerte ($T_A = 25\text{ °C}$)
Characteristics (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Schaltzeiten, I_e von 10% auf 90% und von 90% auf 10%, bei $I_F = 100\text{ mA}$, $R_L = 50\ \Omega$ Switching times, I_e from 10% to 90% and from 90% to 10%, $I_F = 100\text{ mA}$, $R_L = 50\ \Omega$	t_r, t_f	11	ns
Durchlassspannung Forward voltage $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$ $I_F = 1\text{ A}$, $t_p = 100\ \mu\text{s}$	V_F V_F	1.5 (< 1.8) 2.4 (< 3.0)	V V
Sperrstrom Reverse current	I_R	not designed for reverse operation	μA
Gesamtstrahlungsfluss Total radiant flux $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	$\Phi_{e\text{ typ}}$	50	mW
Temperaturkoeffizient von I_e bzw. Φ_e , $I_F = 100\text{ mA}$ Temperature coefficient of I_e or Φ_e , $I_F = 100\text{ mA}$	TC_I	- 0.5	%/K
Temperaturkoeffizient von V_F , $I_F = 100\text{ mA}$ Temperature coefficient of V_F , $I_F = 100\text{ mA}$	TC_V	- 3	mV/K
Temperaturkoeffizient von λ , $I_F = 100\text{ mA}$ Temperature coefficient of λ , $I_F = 100\text{ mA}$	TC_λ	+ 0.3	nm/K

Strahlstärke I_e in Achsrichtung¹⁾

gemessen bei einem Raumwinkel $\Omega = 0.01$ sr

Radiant Intensity I_e in Axial Direction

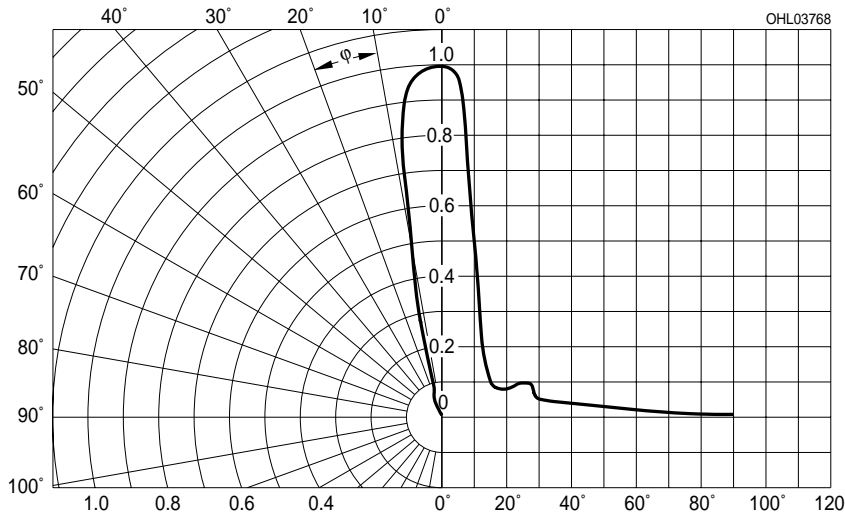
at a solid angle of $\Omega = 0.01$ sr

Bezeichnung Parameter	Symbol	Werte Values			Einheit Unit
		-V	-AW	-BW	
Strahlstärke Radiant intensity $I_F = 100$ mA, $t_p = 20$ ms	$I_{e \text{ min}}$ $I_{e \text{ max}}$	63 125	100 200	160 320	mW/sr mW/sr
Strahlstärke Radiant intensity $I_F = 1$ A, $t_p = 25$ μ s	$I_{e \text{ typ}}$	680	1080	1700	mW/sr

¹⁾ Nur eine Gruppe in einer Verpackungseinheit (Streuung kleiner 2:1) /
Only one bin in one packing unit (variation lower 2:1)

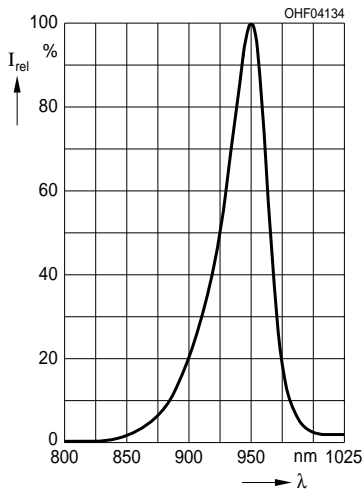
Abstrahlcharakteristik

Radiation Characteristics $I_{rel} = f(\varphi)$



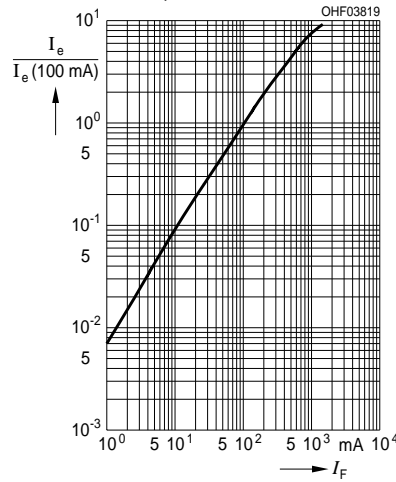
Relative Spectral Emission

$I_{rel} = f(\lambda)$



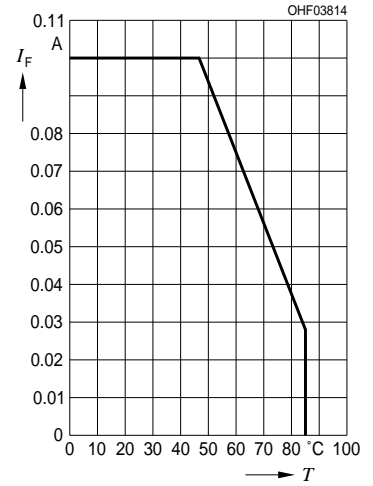
Radiant Intensity $\frac{I_e}{I_e 100 \text{ mA}} = f(I_F)$

Single pulse, $t_p = 25 \mu\text{s}$



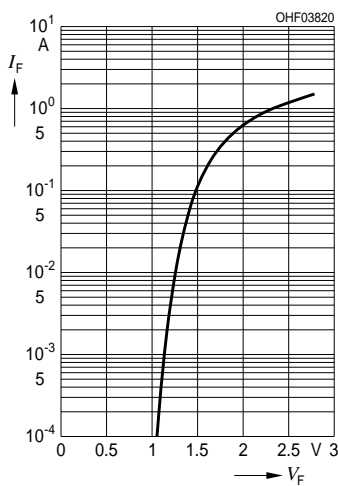
Max. Permissible Forward Current

$I_F = f(T_A), R_{thJA} = 300 \text{ K/W}$



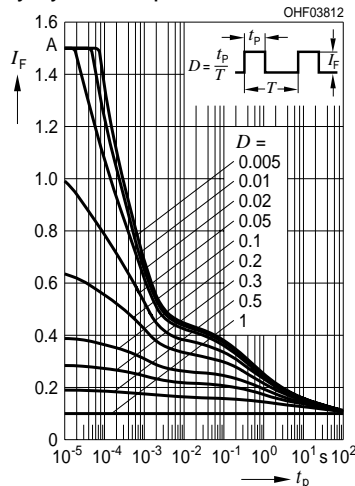
Forward Current

$I_F = f(V_F)$, single pulse, $t_p = 100 \mu\text{s}$



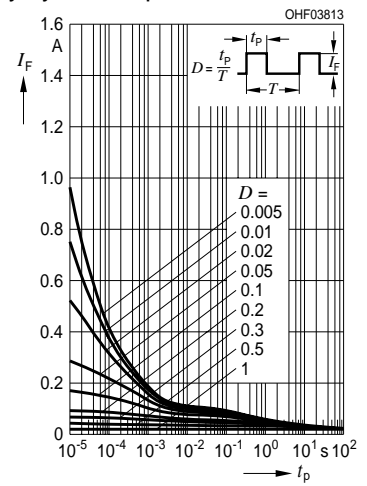
Permissible Pulse Handling Capability

$I_F = f(\tau), T_A = 25 \text{ °C}$, duty cycle $D =$ parameter

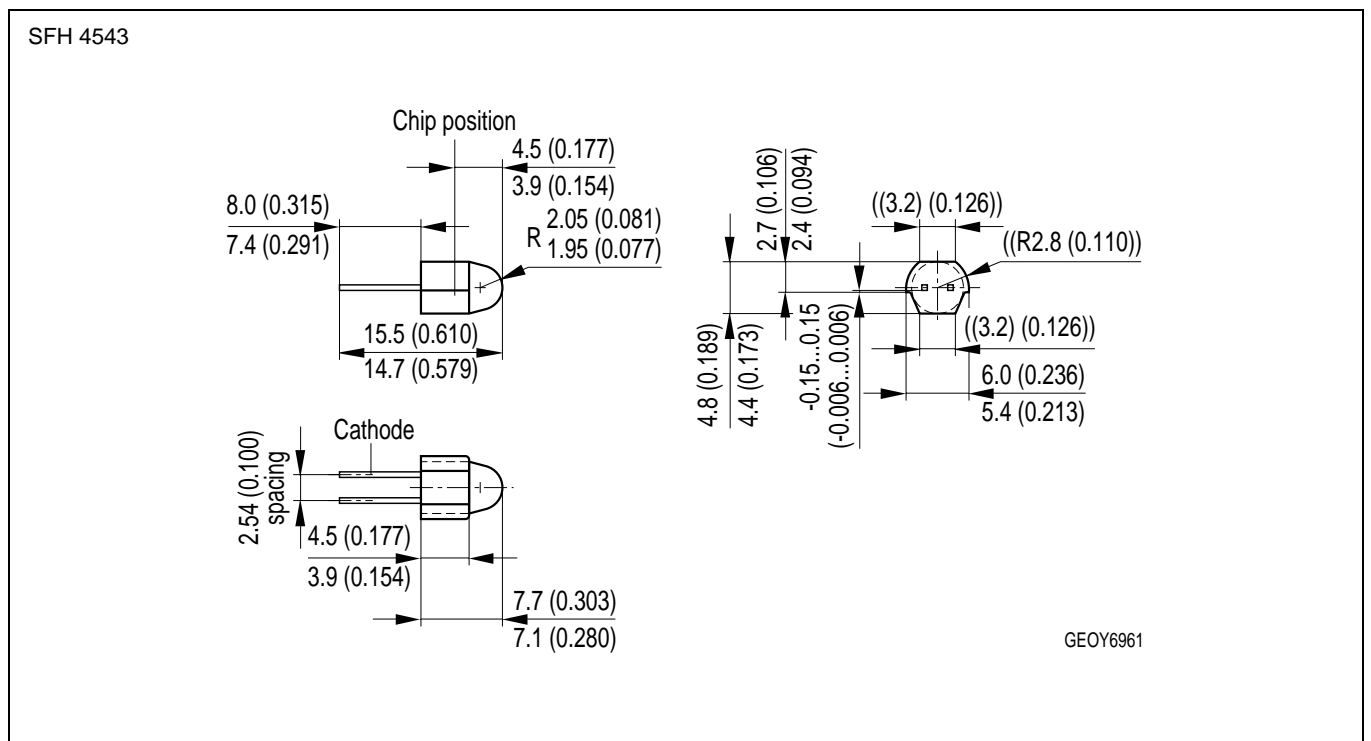
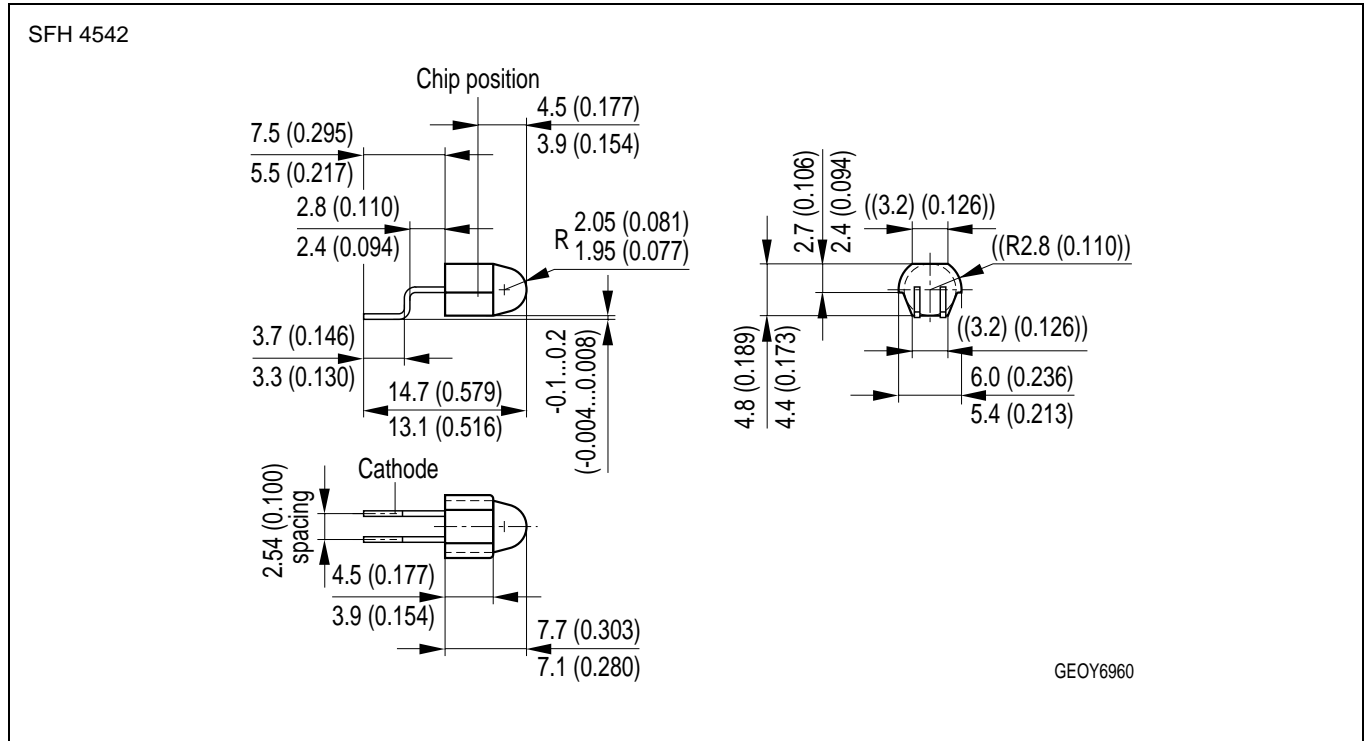


Permissible Pulse Handling Capability

$I_F = f(\tau), T_A = 85 \text{ °C}$, duty cycle $D =$ parameter

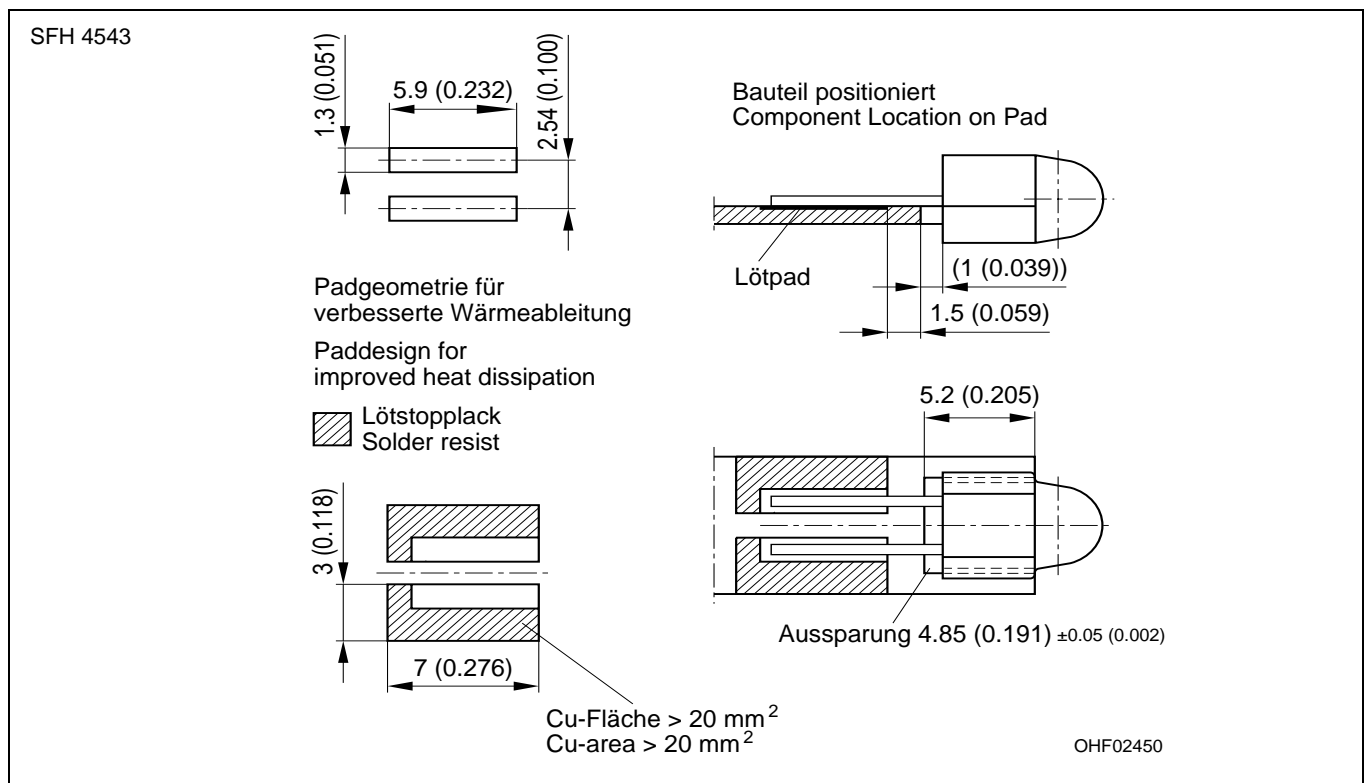
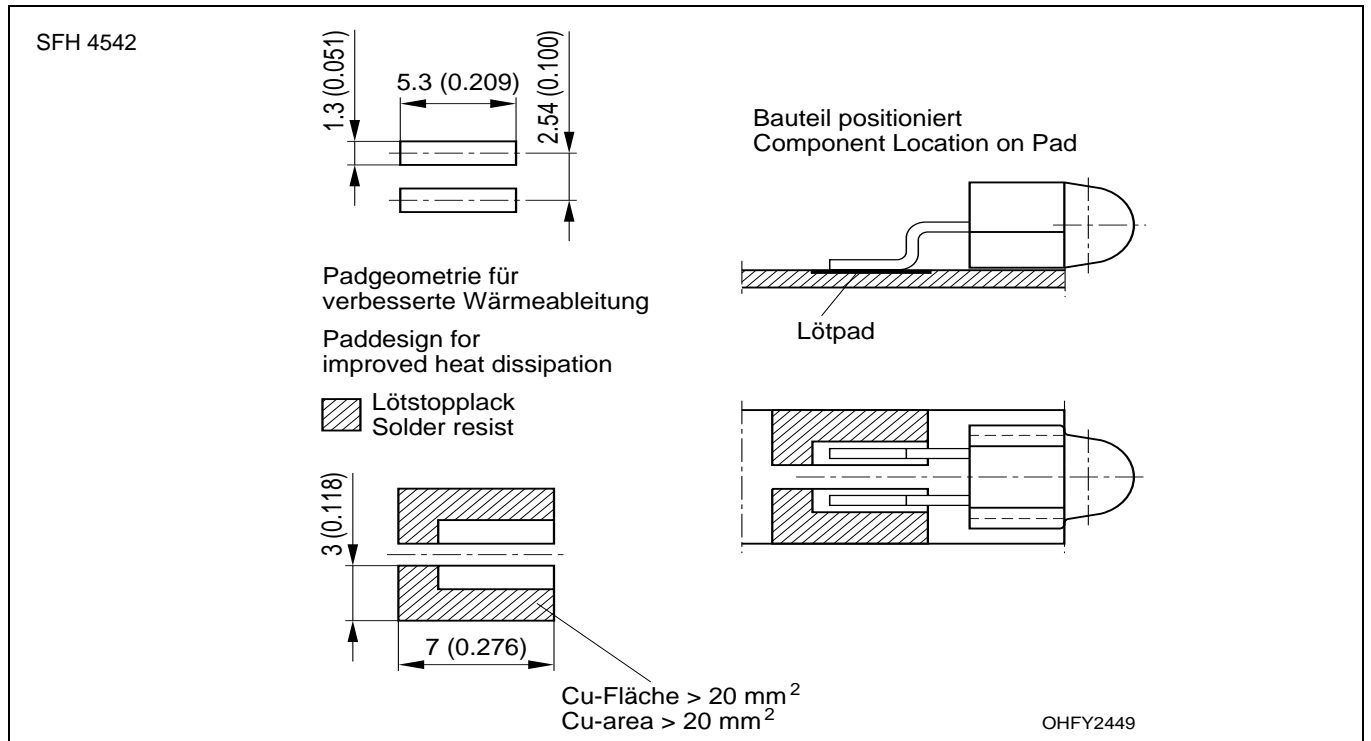


Maßzeichnungen
Package Outlines



Maße in mm (inch) / Dimensions in mm (inch).

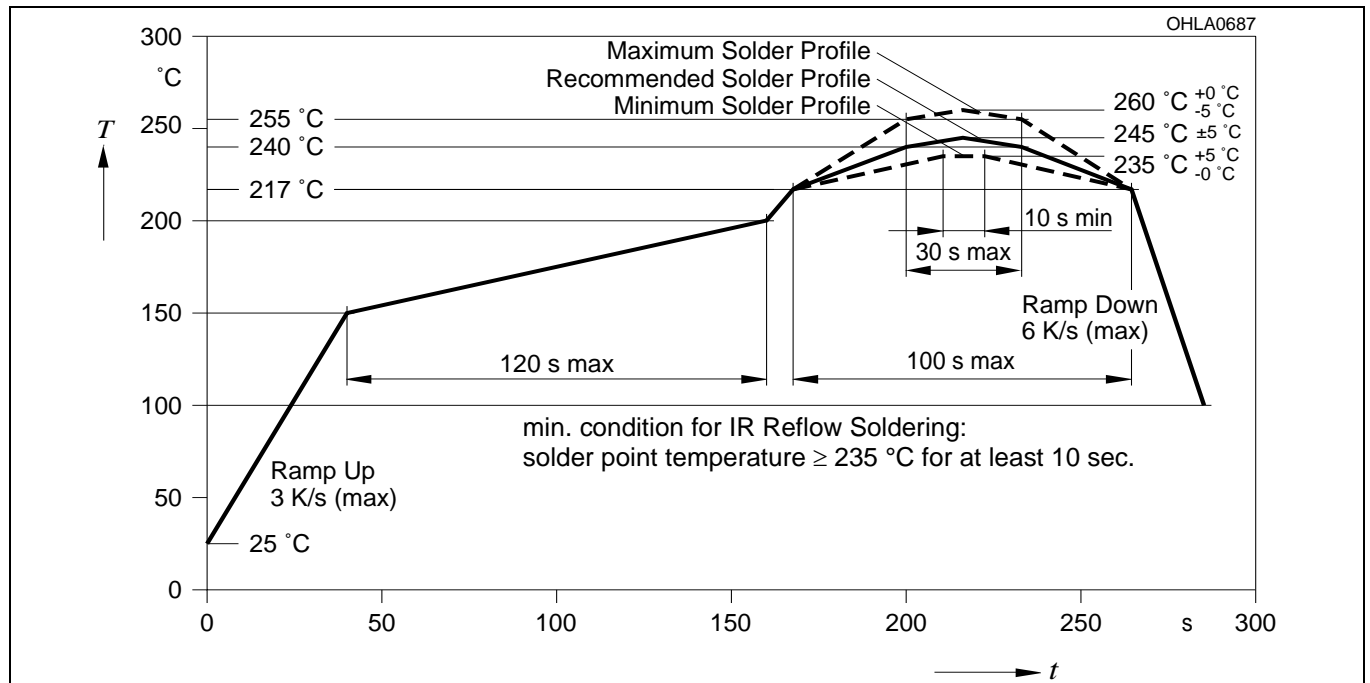
Empfohlenes Lötpaddesign
Recommended Solder Pad



Maße in mm (inch) / Dimensions in mm (inch).

Lötbedingungen
 Soldering Conditions
 Reflow Lötprofil für bleifreies Löten
 Reflow Soldering Profile for lead free soldering

Vorbehandlung nach JEDEC Level 3
 Preconditioning acc. to JEDEC Level 3
 (nach J-STD-020C)
 (acc. to J-STD-020C)



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